

# **Hardware Features**

**Chip Type Industrial Grade** Standard Grade Supplier Starchip Samsung Chip Codes SCM392G S3FS9FG **Electrical Characteristics** 1.6V to 5.5V 1.6V, 3V and 5V Operational Temperature Characteristics -40° to 105°C -25° to 85°C Memory Size available for program and data 136K/256K 340K/440K

### **NVRAM** characteristics

Endurance cycles (min) @ 25° Min. 200MM read/write cycle
Data retention (min) @ 25° 25 Years

Vibration
Passes JESD22-B103

Sector/Bank erase time
1.5ms/3ms
1.5ms/0.4ms
1.5ms/0.4ms

# **Software Features**

#### **Platform**

Technology2G/3G/4G/LTE2G/3G/4G/LTEUICCRelease 8Release 8Java Card2.2.1 or higher2.2.1 or higherGlobal Platform2.2.12.2.1

#### Supported Applications

SIM Release 4 Release 4
USIM Release 8 Release 8
ISIM Release 8 Release 8
HPSIM Release 8

# **OTA Capabilities**

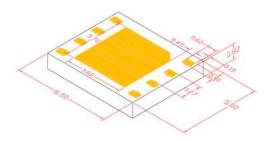
Remote File Management Release 8 Release 8 Renote Applet Management Release 8 Release 8

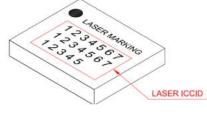
# **SIM Card Physical Characteristics**

### Embedded Form Factor (MFF2)

Module FormatMFF2 (QFN8) embedded.Size6 x 5mm\*, (height: 0.75-0.82mm)StandardTS 102.671 - standardized formatFittingSoldered to circuit boardTransportationOn trays/reels/boxes

# Technical Details (MFF2)







# **SIM Card Physical Characteristics**



2FF - Mini SIM

Height: 25mm Width: 15mm Thickness: 0.76mm



3FF - Micro SIM

Height: 15mm Width: 12mm Thickness: 0.76mm



4FF - Nano SIM

Height: 12.3mm Width: 8.8mm Thickness: 0.67mm

# **Embedded SIM QNF8 Pinout**

